12 January 7004

Updated Search

09/836,844

12 Janua	wy 2004	Updated Search		09/856,
L Number	Hits	Search Text	DB	Time stamp
-	4	6214193.pn. 6099702.pn.	USPAT;	2003/04/25
!			US-PGPUB;	11:32
			EPO; JPO;	
		-	DERWENT	
-	2	3950184.pn.	USPAT;	2003/04/25
		·	US-PGPUB;	11:58
			EPO; JPO;	
			DERWENT	
<u>-</u>	14	3950184.URPN.	USPAT	2003/04/25
				11:58
-	5	("3141793"   "3656173"   "3950184"   "4451507"	USPAT	2003/04/25
		"5084483").PN.		12:01
-	17	("3798056"   "3950184"   "4339319"   "4373988"	USPAT	2003/04/25
		"4466864"   "4856456"   "5000827"   "5169408"		13:58
		"5312487"   "5340437"   "5472592"   "5670034"		
		"5677000"   "5893966"   "5930549"   "6077412"		
		"6099702").PN.		
-	33	5000827.URPN.	USPAT	2003/04/25
				12:04
-	53	5169408.URPN.	USPAT	2003/04/25
				12:41
-	33	5000827.URPN.	USPAT	2003/04/25
				12:50
_	2247	204/212,225,237,275.1.ccls.	USPAT;	2003/04/25
			US-PGPUB;	13:58
			EPO; JPO;	
			DERWENT	
-	773	204/224r.ccls.	USPAT;	2003/04/25
			US-PGPUB;	13:58
			EPO; JPO;	
			DERWENT	
-	2837	204/212,225,237,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/25
			US-PGPUB;	14:00
			EPO; JPO;	
×.			DERWENT	
_	2190	118/416,500,501.ccls.	USPAT;	2003/04/25
•			US-PGPUB;	14:01
			EPO; JPO;	· =
			DERWENT	
_	5015	(204/212,225,237,275.1.ccls. 204/224r.ccls.)	USPAT;	2003/04/25
		118/416,500,501.ccls.	US-PGPUB;	14:01
			EPO; JPO;	
			DERWENT	
_	1027	((204/212,225,237,275.1.ccls. 204/224r.ccls.)	USPAT;	2003/04/25
	1067	118/416,500,501.ccls.) and (semiconductor or wafer)	US-PGPUB;	14:02
		110, 110,000,001.ccis., and (semiconductor of water)	EPO; JPO;	1-1.UL
	;		DERWENT	
_	557	(((204/212,225,237,275.1.ccls. 204/224r.ccls.)	USPAT;	2003/04/25
-	557	(((204/212,225,237,275.1.ccis. 204/224r.ccis.) 118/416,500,501.ccls.) and (semiconductor or wafer))		2003/04/25
			US-PGPUB;	14:02
		and (spinning or spin or spun or rotate or rotated or	EPO; JPO;	
		rotating)	DERWENT	

·		<u> </u>	T	
-	90	((((204/212,225,237,275.1.ccls. 204/224r.ccls.)	USPAT;	2003/04/25
		118/416,500,501.ccls.) and (semiconductor or wafer))	US-PGPUB;	14:36
		and (spinning or spin or spun or rotate or rotated or	EPO; JPO;	
		rotating)) and (recycle or recycling or recylcer or	DERWENT	
		reclaim or reclamation or recycled or reclaimed or		
		recover or recovered or recovery or recovering)		
-	3	("5922138"   "6168691"   "6187152").PN.	USPAT	2003/04/25
		(050/00 UDD))		14:29
-	0	6352623.URPN.	USPAT	2003/04/25
	277/	005 400 400 457 000 1. 407 00 000 250 1.	LICDAT	14:33
-	3776	205/122,123,157,220.ccls. 427/98,299,352.ccls.	USPAT;	2003/04/25
			US-PGPUB;	14:34
			EPO; JPO; DERWENT	
	940	(205/122 122 157 220 4 427/09 200 252 4 )	USPAT;	2003/04/25
-	940	(205/122,123,157,220.ccls. 427/98,299,352.ccls.) and (semiconductor or wafer)	US-PGPUB;	14:34
		and (semiconductor or water)	EPO; JPO;	14.54
			DERWENT	
_	504	((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
	304	and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:35
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	14.55
		washing or washed)	DERWENT	
_	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:36
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)) and (recycle or recycling or	DERWENT	
		recylcer or reclaim or reclamation or recycled or		
		reclaimed or recover or recovered or recovery or		
		recovering)		
_	90	((((204/212,225,237,275.1.ccls. 204/224r.ccls.)	USPAT;	2003/04/25
		118/416,500,501.ccls.) and (semiconductor or wafer))	US-PGPUB;	15:01
		and (spinning or spin or spun or rotate or rotated or	EPO; JPO;	
		rotating)) and (recycle or recycling or recycler or	DERWENT	
		reclaim or reclamation or recycled or reclaimed or		
		recover or recovered or recovery or recovering)		
-	53	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:37
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)) and (recycle or recycling or	DERWENT	
		recycler or reclaim or reclamation or recycled or		
		reclaimed or recover or recovered or recovery or		
		recovering)		
-	225	(((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
		and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:37
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	
		washing or washed)) and (spin or spinning or spun or	DERWENT	
		rotate or rotating or rotated or revolve or revolved or		
		revolving)		

	40	((((205/122,123,157,220.ccls. 427/98,299,352.ccls.)	USPAT;	2003/04/25
-	40	and (semiconductor or wafer)) and (cleaning or clean	US-PGPUB;	14:37
		or cleaned or rinsed or rinse or rinsing or wash or	EPO; JPO;	14.57
		washing or washed)) and (spin or spinning or spun or	DERWENT	
		rotate or rotating or rotated or revolve or revolved or	DERWEINT	
		_		:
		revolving)) and (recycle or recycling or recycler or		
		reclaim or reclamation or recycled or reclaimed or		
		recover or recovered or recovery or recovering)		0000101110
-	11	(U5-6099702-\$ or US-6214193-\$ or US-5677000-\$	USPAT;	2003/06/10
		or US-3950184-\$ or US-6551487-\$ or	US-PGPUB;	11:50
		US-6299751-\$).did.	EPO; JPO;	
			DERWENT	
-	1	2000wo-us28210.ap,prai.	USPAT;	2003/06/10
			US-PGPUB;	11:53
			EPO; JPO;	
			DERWENT	
-	16	6099702.URPN.	USPAT	2003/06/10 11:51
-	15	("3798056"   "3950184"   "4339319"   "4373988"	USPAT	2003/06/10 11:51
		"4466864"   "4856456"   "5000827"   "5169408"		
		"5312487"   "5340437"   "5472592"   "5670034"		
		"5677000"   "5893966"   "5930549").PN.		
_	0	6214193.URPN.	USPAT	2003/06/10 11:51
_	17	("3798056"   "3950184"   "4339319"   "4373988"	USPAT	2003/06/10 11:51
		"4466864"   "4856456"   "5000827"   "5169408"		
		"5312487"   "5340437"   "5472592"   "5670034"		
		"5677000"   "5893966"   "5930549"   "6077412"		
		"6099702").PN.		·
_	33	6099702.URPN. (("3798056"   "3950184"	USPAT;	2003/06/10 11:51
		"4339319"   "4373988"   "4466864"   "4856456"	US-PGPUB;	
		"5000827"   "5169408"   "5312487"   "5340437"	EPO; JPO;	
		"5472592"   "5670034"   "5677000"   "5893966"	DERWENT	
		"5930549").PN.) 6214193.URPN. (("3798056"	JE. 111 C. 11	
		"3950184"   "4339319"   "4373988"   "4466864"		
		"4856456"   "5000827"   "5169408"   "5312487"		
		"5340437"   "5472592"   "5670034"   "5677000"		
		"5893966"   "5930549"   "6077412"		
		5893900   5930549   6077412     "6099702").PN.)		
			DEDWENT	2002/04/10
-	1	2001-580725.NRAN.	DERWENT	2003/06/10
	40	(/II/120702II) (II/090201II) (II5022077II) -	LICDAŤ:	11:52
-	12	(("6139703") or ("6080291") or ("5932077") or	USPAT;	2003/06/10
		("5447615") or ("5421987") or ("5344491")).PN.	US-PGPUB;	12:29
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	836844.apn.	USPAT;	2003/06/10
1			US-PGPUB;	12:47
	]		EPO; JPO;	
1			DERWENT;	
			IBW_LDB	
-	2401	204/199,212,232,263,275.1,297.01,297.06,297.07,297		2003/06/10
			U5-PGPUB;	12:48
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	

-	780	204/224r.ccls.	USPAT;	2003/06/10
		·	US-PGPUB;	12:48
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	3033	204/199,212,232,263,275.1,297.01,297.06,297.07,297	_	2003/06/10
		204/224r.ccls.	US-PGPUB;	12:48
		LO 17 LL 11.0010.	EPO; JPO;	12.10
		·	DERWENT;	
			1	
		(004,400,040,000,040,007,4,007,04,007,04,007,07,07,07	IBM_TDB	0000/07/40
-	73	(204/199,212,232,263,275.1,297.01,297.06,297.07,29	i e	2003/06/10
		204/224r.ccls.) and ((multiple or plural\$3 or second)	US-PGPUB;	12:49
		near (outlet or withdraw\$3 or collect\$4))	EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	26	(204/199,212,232,263,275.1,297.01,297.06,297.07,29	7.085PA(3.;	2003/06/10
		204/224r.ccls.) and ((multiple or plural\$3) near	US-PGPUB;	12:49
		(outlet or withdraw\$3 or collect\$4))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	47	((204/199,212,232,263,275.1,297.01,297.06,297.07,29	_	2003/06/10
	7′	204/224r.ccls.) and ((multiple or plural\$3 or second)	US-PGPUB;	12:52
				12.32
		near (outlet or withdraw\$3 or collect\$4))) not	EPO; JPO;	
		((204/199,212,232,263,275.1,297.01,297.06,297.07,29		
		204/224r.ccls.) and ((multiple or plural\$3) near	IBW_TDB	
		(outlet or withdraw\$3 or collect\$4)))		
-	16	(204/199,212,232,263,275.1,297.01,297.06,297.07,29		2003/06/10
		204/224r.ccls.) and (situ near (rins\$3 or process\$3	US-PGPUB;	12:56
		or clean\$3 or wash\$3))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	5932077.pn.	USPAT;	2004/01/07
		'	US-PGPUB;	14:58
-			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	25	5932077.URPN.	USPAT	2004/01/07
	23	070E0/ / .ON IV.	0017.1	14:58
	64	201/108 100 calc and (micro-lastronia an wafe-	USPAT;	2004/01/07
-	54	204/198,199.ccls. and (microelectronic or wafer or	1	
		semiconductor)	US-PGPUB;	15:12
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	18	204/198,199.ccls. and (microelectronic or wafer or	USPAT;	2004/01/07
		semiconductor) and (spray\$4)	US-PGPUB;	15:12
			EPO; JPO;	
	-		DERWENT;	
			IBM_TDB	
-	2342	204/212,225,237,275.1.ccls.	USPAT;	2004/01/08
			US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT	
L			DCV AA CIA I	

-	811	204/224r.ccls.	USPAT;	2004/01/08
			US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT	
_	2957	204/212,225,237,275.1.ccls. 204/224r.ccls.	USPAT;	2004/01/08
			US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT	
_	373	(204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)	US-PGPUB;	09:19
			EPO; JPO;	
			DERWENT	
_	8	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)) and	U5-PGPUB;	09:19
		(tilt\$5 and spray\$5)	EPO; JPO;	
		(migo and spraygo)	DERWENT	
_	14	((204/212,225,237,275.1.ccls. 204/224r.ccls.) and	USPAT;	2004/01/08
		(wafer or semiconductor or microelectronic)) and	U5-PGPUB;	10:12
		(tilt\$5 and (spray\$5 or nozzle))	EPO; JPO;	10.12
		(Timps and (Sprayups or Hozzie))	DERWENT	
	100	(204/198-227.ccls. and (microelectronic or wafer or	USPAT;	2004/01/08
	100	semiconductor)) and ((contact or electrode or	US-PGPUB;	11:48
		cathode) with (clean\$3 or wash\$3 or rins\$5))	EPO; JPO;	11.40
		carnode) with (cleans of washes of this \$3))	DERWENT	
	2	4154147 min	USPAT;	2004/01/08
-		6156167.pn.	1	
			US-PGPUB;	11:48
			EPO; JPO;	
		02/044	DERWENT	2004/01/00
-	1	836844.apn.	USPAT;	2004/01/09
			US-PGPUB;	09:24
		,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/04/00
-	438	204/198-227.ccls. and (microelectronic or wafer or	USPAT;	2004/01/09
		semiconductor)	US-PGPUB;	09:53
			EPO; JPO;	
			DERWENT	
-	20	(204/198-227.ccls. and (microelectronic or wafer or	USPAT;	2004/01/09
		semiconductor)) and (tilt\$4 with (wafer or substrate	US-PGPUB;	09:53
		or semiconductor or microelectronic))	EPO; JPO;	
			DERWENT	
-	5	6613214.pn. 6258220.pn.	USPAT;	2004/01/09
			US-PGPUB;	09:44
			EPO; JPO;	
			DERWENT	
-	3	6251236.pn. 6258220.pn.	USPAT;	2004/01/09
			US-PGPUB;	09:44
			EPO; JPO;	
			DERWENT	
-	11422	(205/\$.ccls. or 204/\$.ccls.) and (microelectronic or	USPAT;	2004/01/09
		wafer or semiconductor)	US-PGPUB;	09:53
			EPO; JPO;	
			DERWENT	

-	121	((205/\$.ccls. or 204/\$.ccls.) and (microelectronic or	USPAT;	2004/01/09
		wafer or semiconductor)) and (tilt\$4 with (wafer or	US-PGPUB;	09:54
		substrate or semiconductor or microelectronic))	EPO; JPO;	
			DERWENT	
_	101	(((205/\$.ccls. or 204/\$.ccls.) and (microelectronic or	USPAT;	2004/01/09
		wafer or semiconductor)) and (tilt\$4 with (wafer or	US-PGPUB;	09:54
		substrate or semiconductor or microelectronic))) not	EPO; JPO;	
		((204/198-227.ccls. and (microelectronic or wafer or	DERWENT	
		semiconductor)) and (tilt\$4 with (wafer or substrate		
		or semiconductor or microelectronic)))		